

SOT-89-3L Plastic-Encapsulate MOSFETS

N-Channel Enhancement Mode Power MOSFET

Features:

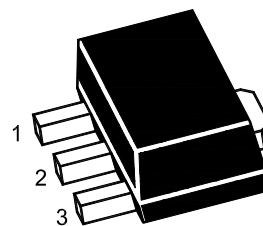
- High density cell design for ultra low $R_{DS(on)}$
- Excellent package for good heat dissipation
- $V_{DS} = 100V, I_D = 2A$
 $R_{DS(on)} < 240m\Omega @ V_{GS} = 10V$

Applications:

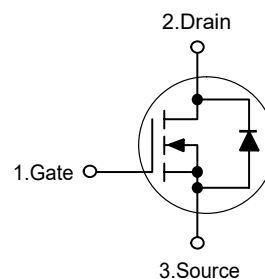
- Power Switching Application
- Uninterruptible Power Supply

Marking Code: 0102Q

SOT-89-3L



1. Gate 2. Drain 3. Source



Absolute Maximum Ratings

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	2	A
Drain Current-Pulsed ^{Note1}	I_{DM}	5	A
Maximum Power Dissipation	P_D	1.2	W
Junction Temperature	T_J	150	°C
Storage Temperature Range	T_{STG}	-55 to +150	°C

Thermal Characteristics

Thermal Resistance, Junction-to-Ambient ^{Note2}	$R_{\theta JA}$	104	°C/W
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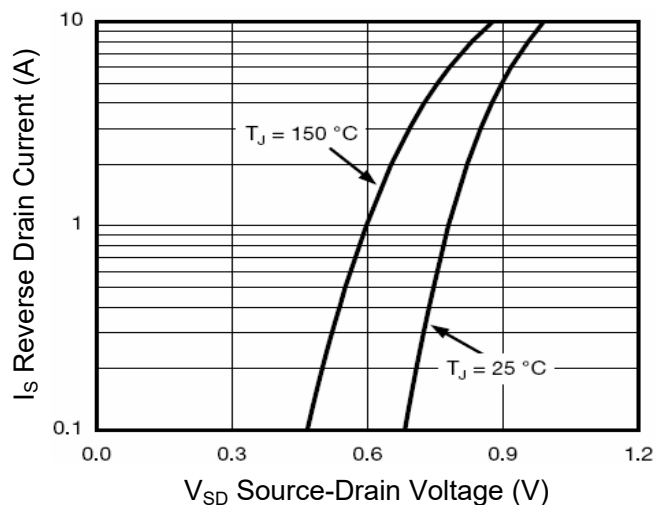
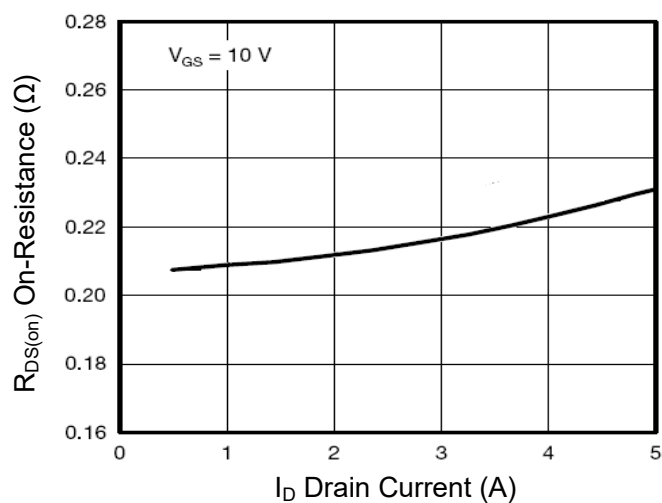
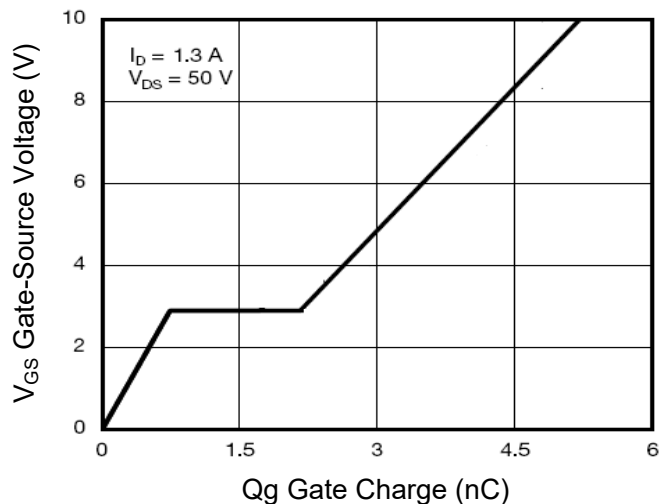
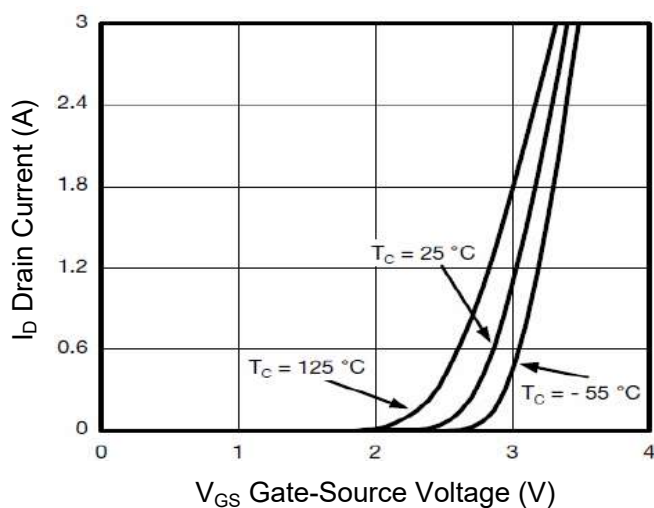
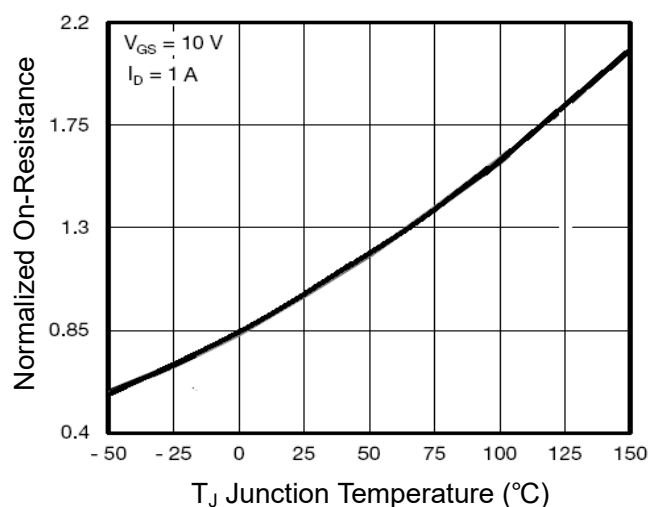
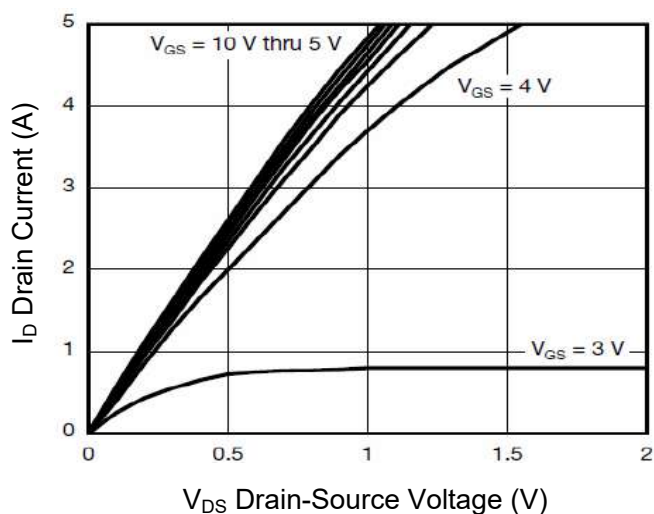
Electrical Characteristics

(Ta=25°C unless otherwise specified)

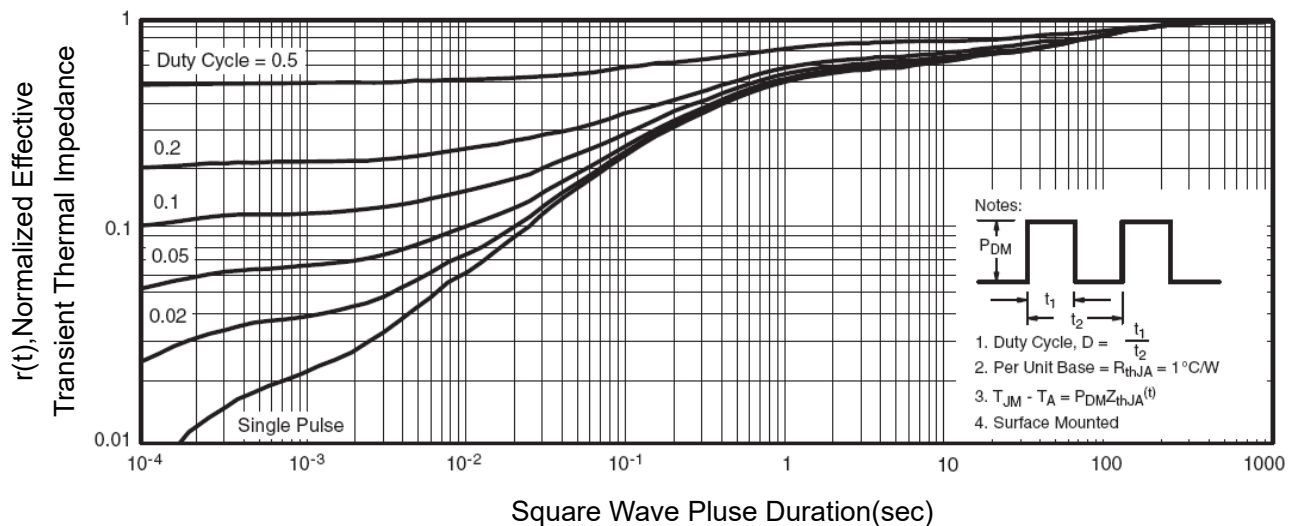
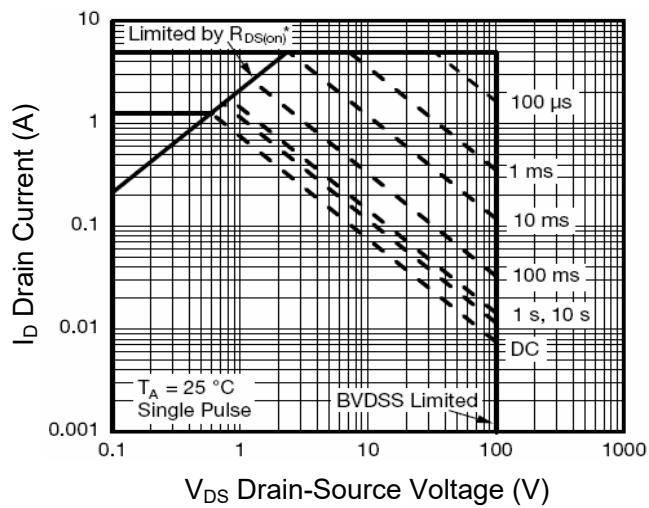
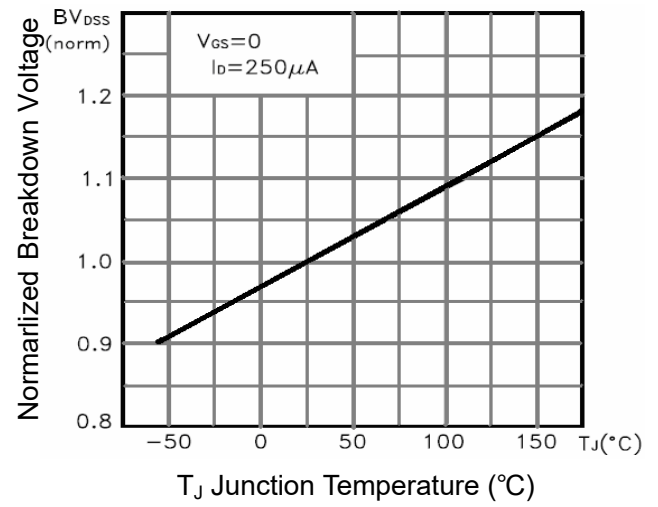
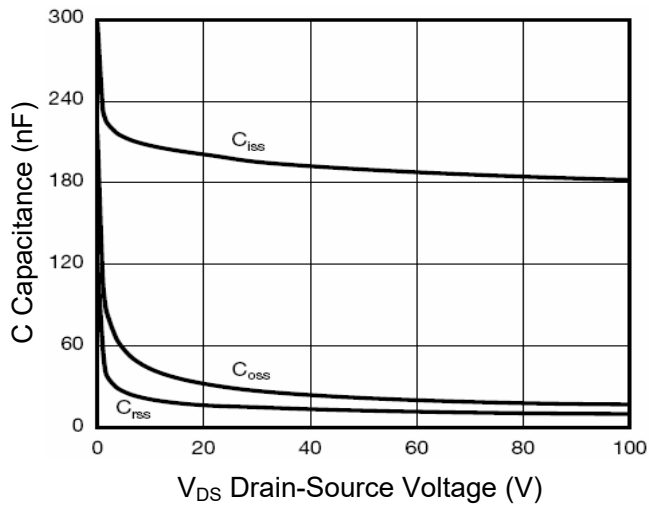
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	100	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$	--	--	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	--	--	± 100	nA
Gate Threshold Voltage ^{Note3}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2	1.8	2.5	V
Drain-Source On-Resistance ^{Note3}	$R_{DS(on)}$	$V_{GS}=10V, I_D=1A$	--	210	240	m Ω
Forward Transconductance ^{Note3}	g_{FS}	$V_{DS}=5V, I_D=1A$	1	--	--	S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=50V, V_{GS}=0V, f=1MHz$	--	190	--	pF
Output Capacitance	C_{oss}		--	22	--	pF
Reverse Transfer Capacitance	C_{rss}		--	13	--	pF
Switching Characteristics						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V, I_D=1.3A, R_L=39\Omega$ $V_{GS}=10V, R_{GEN}=1\Omega$	--	6	--	nS
Turn-on Rise Time	t_r		--	10	--	nS
Turn-off Delay Time	$t_{d(off)}$		--	10	--	nS
Turn-off Fall Time	t_f		--	6	--	nS
Total Gate Charge	Q_g	$V_{DS}=50V, I_D=1.3A, V_{GS}=10V$	--	5.2	--	nC
Gate-Source Charge	Q_{gs}		--	0.75	--	nC
Gate-Drain Charge	Q_{gd}		--	1.4	--	nC
Source-Drain Diode Characteristics						
Diode Forward Voltage ^{Note3}	V_{SD}	$V_{GS}=0V, I_S=1.3A$	--	--	1.2	V
Diode Forward Current ^{Note2}	I_S		--	--	2	A

Note: 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

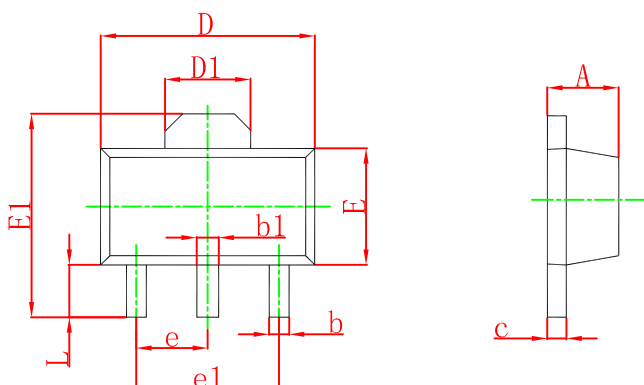
Typical Characteristic Curves



Typical Characteristics

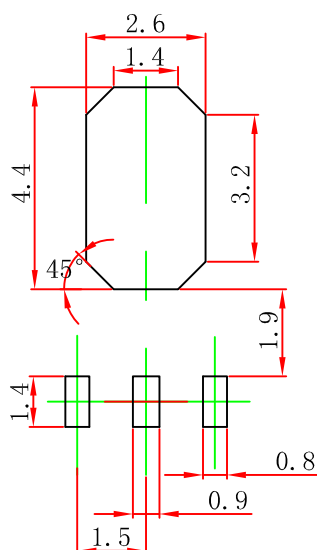


SOT 89 3L Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF.		0.061 REF.	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500 TYP.		0.060 TYP.	
e1	3.000 TYP.		0.118 TYP.	
L	0.900	1.200	0.035	0.047

SOT-89-3L Suggested Pad Layout



Note:
 1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.